

GENERAL DESCRIPTION

The HM2309 is the P-Channel logic enhancement mode power field effect transistors are produced using high cell density, DMOS trench technology. This high density process is especially tailored to minimize on-state resistance.

FEATURES

- $R_{DS(ON)} \leq 215m\Omega @ V_{GS} = -10V$
- $R_{DS(ON)} \leq 260m\Omega @ V_{GS} = -4.5V$
- Super high density cell design for extremely low $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability
- Capable doing Cu wire bonding

APPLICATIONS

- Power Management
- Portable Equipment
- Battery Powered System
- Load Switch

Absolute Maximum Ratings (TA=25°C Unless Otherwise Noted)

Parameter	Symbol	Maximum Ratings	Unit
Drain-Source Voltage	V_{DS}	-60	V
Gate-Source Voltage	V_{GS}	±20	V



Electrical Characteristics ($T_j = 25^\circ\text{C}$ Unless Otherwise Specified)

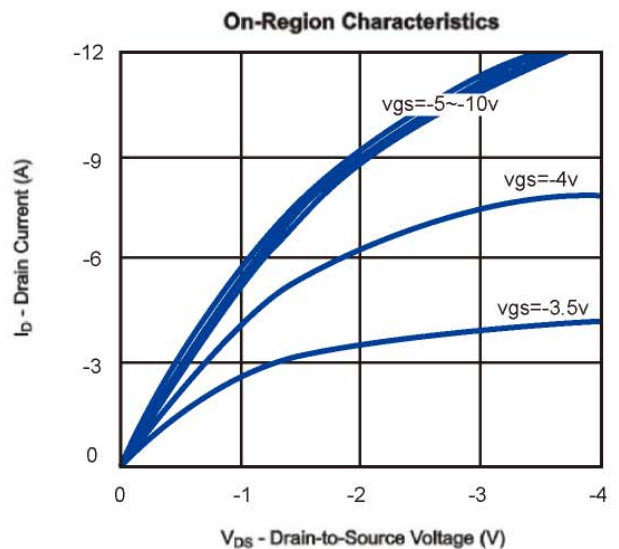
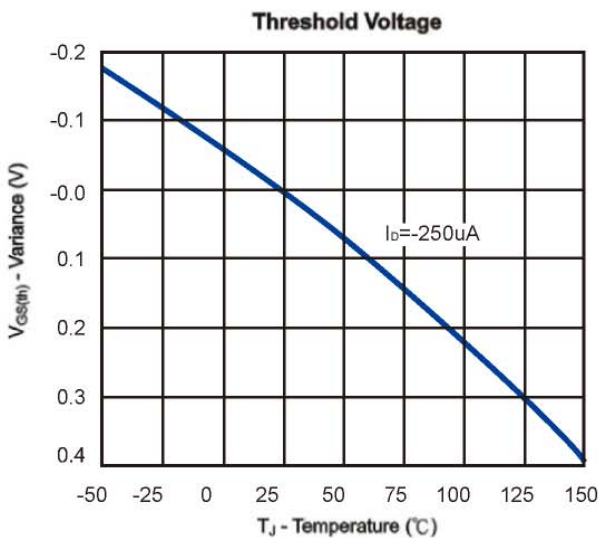
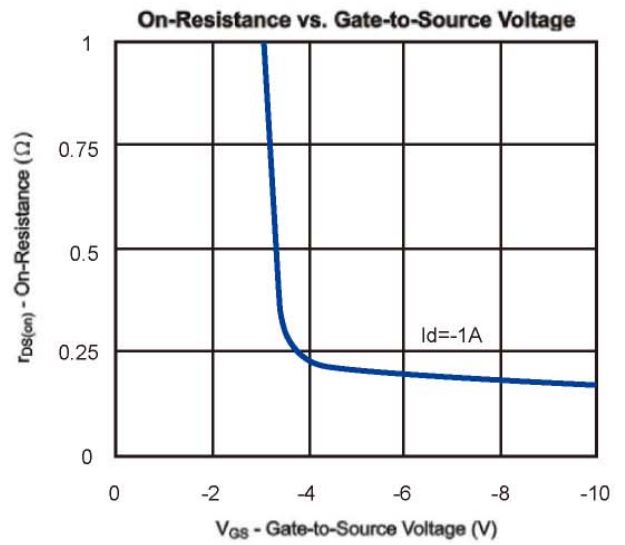
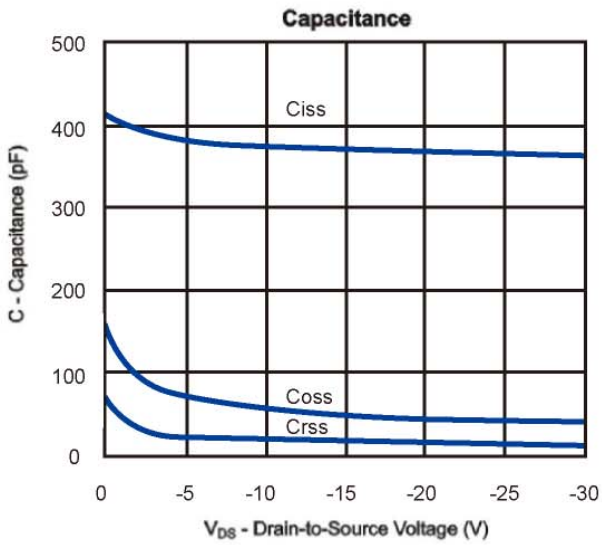
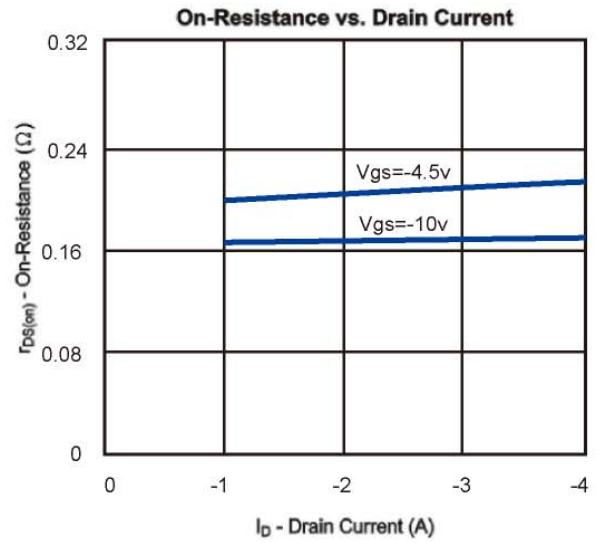
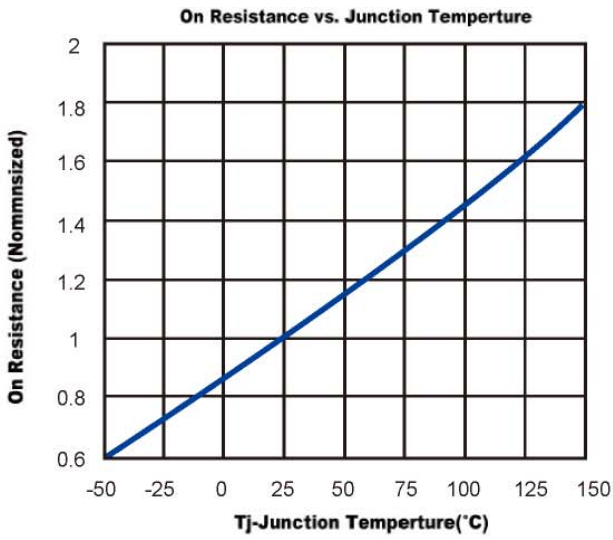
Symbol	Parameter	Limit	Min	Typ	Max	Unit
STATIC						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\ \mu A$	-60			V
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\ \mu A$	-1		-3	V
I_{GSS}	Gate Leakage Current	$V_{DS}=0V, V_{GS}=\pm 20V$			± 100	nA
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=-60V, V_{GS}=0V$			-10	μA
$R_{DS(ON)}$	Drain-Source On-Resistance	$V_{GS}=-10V, I_D=-1.8A$		170	215	m Ω
		$V_{GS}=-4.5V, I_D=-1.4A$		200	260	
V_{SD}	Diode Forward Voltage	$I_S=-1.2A, V_{GS}=0V$			-1.2	V
DYNAMIC						
Q_g	Total Gate Charge	$V_{DS}=-48, V_{GS}=-4.5V, I_D=-1A$		6.3		nC
Q_{gs}	Gate-Source Charge			2.3		
Q_{gd}	Gate-Drain Charge			1.8		
R_g	Gate Resistance	$V_{DS}=0V, V_{GS}=0V, f=1MHz$		9.8		Ω
$t_{d(on)}$	Turn-On Delay Time	$V_{DS}=-30V, R_L=30\ \Omega$ $R_{GEN}=3.3\ \Omega, V_{GS}=-10V$ $I_D=-1A$		20		ns
t_r	Turn-On Rise Time			33.1		
$t_{d(off)}$	Turn-Off Delay Time			5.2		
t_f	Turn-Off Fall Time			3.8		
C_{iss}	Input Capacitance	$V_{DS}=-25V, V_{GS}=0V, f=1MHz$		364		pF
C_{oss}	Output Capacitance			41		
C_{rss}	Reverse Transfer Capacitance			12		

Notes: a. Based on epoxy or solder paste and bond wire Au or Cu 2mil×2(S), Au or Cu 2mil×1 (G) on each die of SOT-23 (SC-59) package.

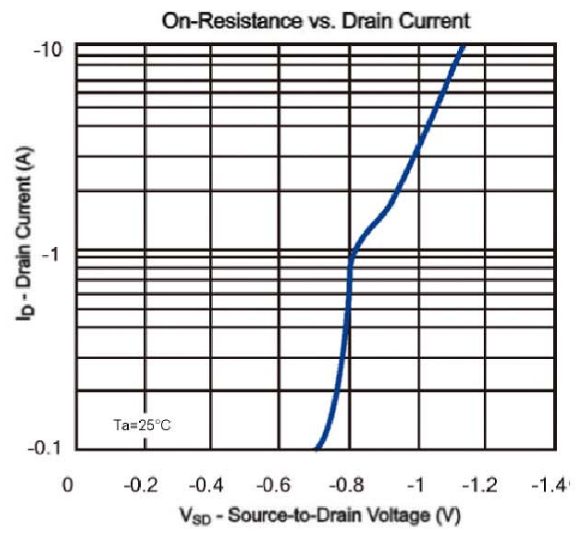
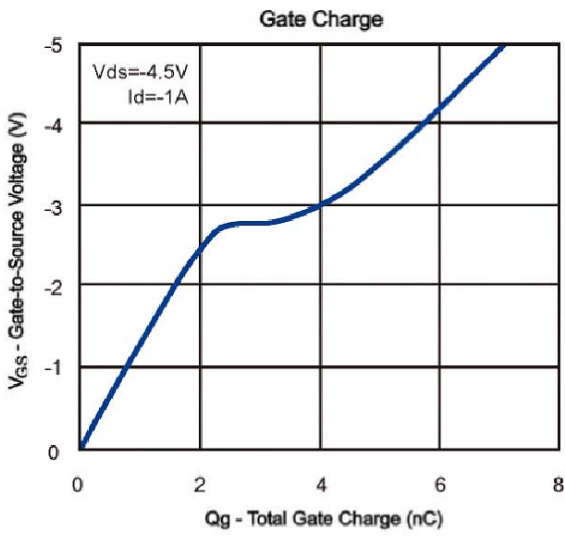
b. Pulse test; pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.

c. H&M SEMI reserves the right to improve product design, functions and reliability without notice.

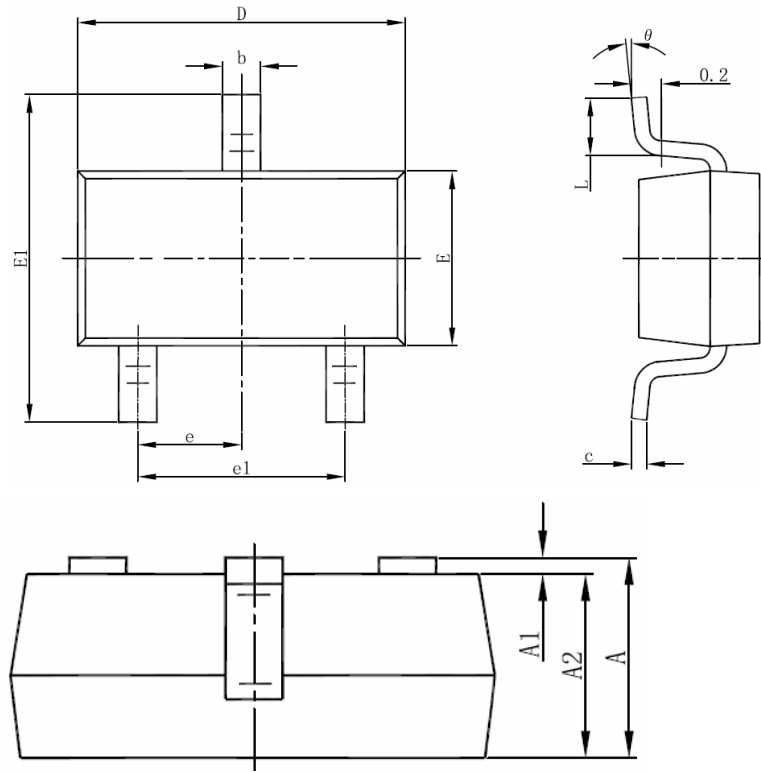
Typical Characteristics (T_J = 25°C Noted)



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SOT-23-3L PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

NOTES

- All dimensions are in millimeters.
- Tolerance $\pm 0.10\text{mm}$ (4 mil) unless otherwise specified.
- Package body sizes exclude mold flash and gate burrs. Mold flash at the non-lead sides should be less than 5 mils.
- Dimension L is measured in gauge plane.
- Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.